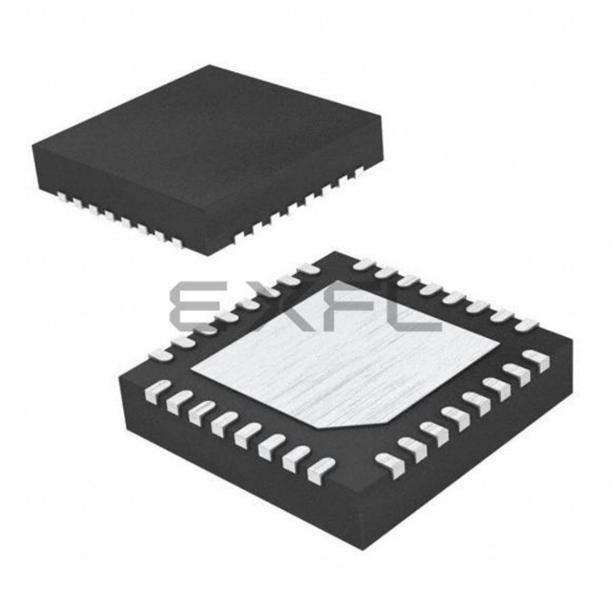
Microchip Technology - PIC24EP32MC202T-E/MM Datasheet



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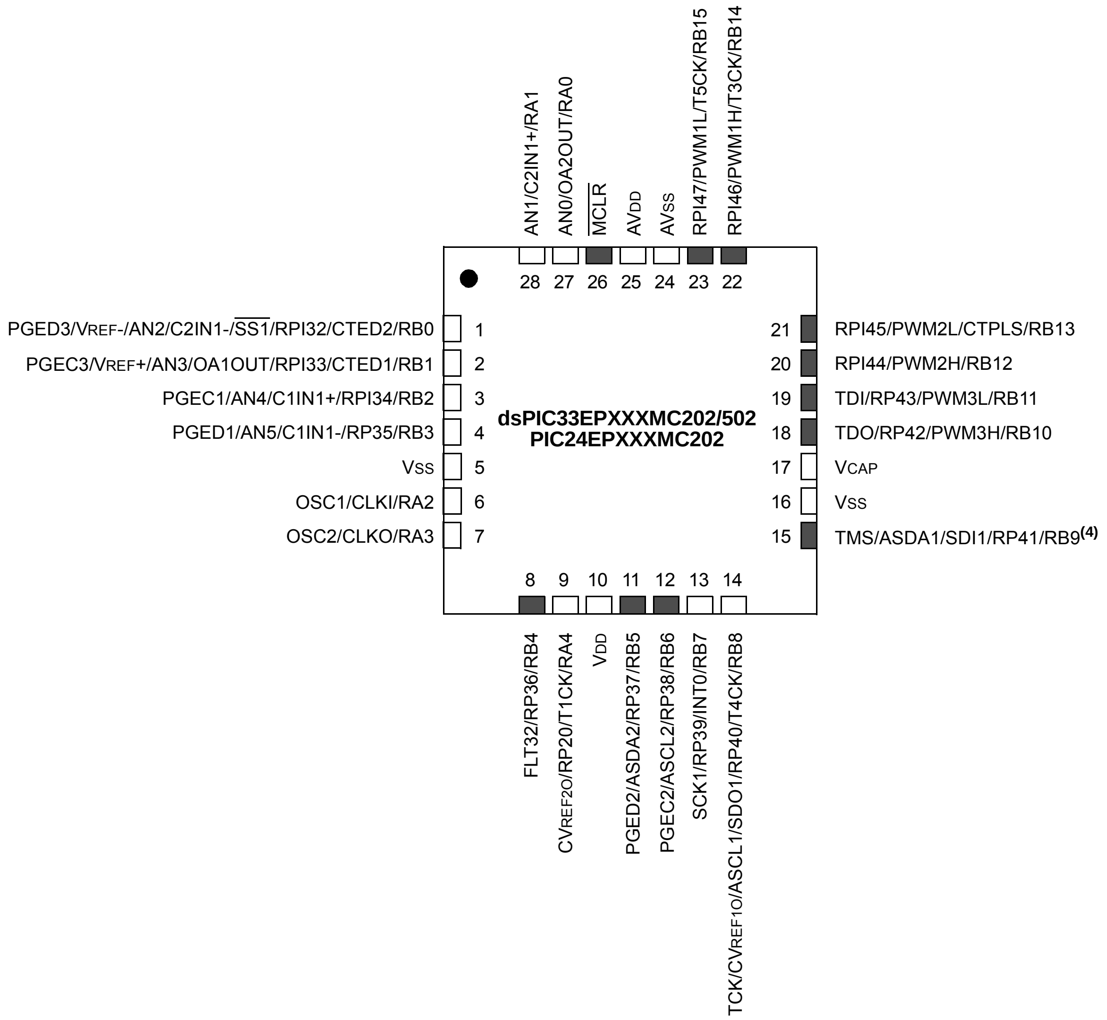
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	32KB (10.7K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN-S (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep32mc202t-e-mm

Pin Diagrams (Continued)

28-Pin QFN-S[1,2,3]

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

1.0 DEVICE OVERVIEW

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive resource. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com)

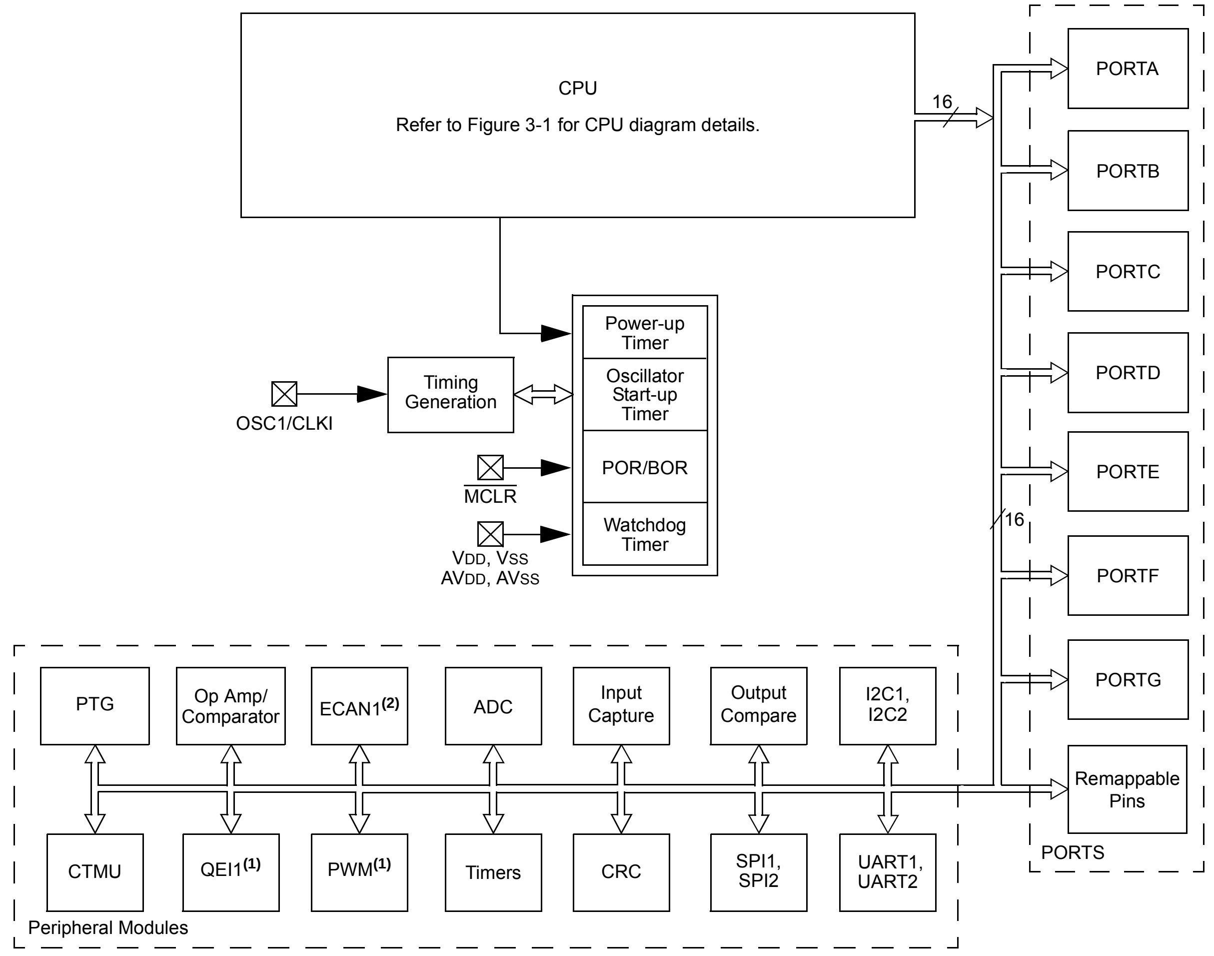
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This document contains device-specific information for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X Digital Signal Controller (DSC) and Microcontroller (MCU) devices.

dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices contain extensive Digital Signal Processor (DSP) functionality with a high-performance, 16-bit MCU architecture.

Figure 1-1 shows a general block diagram of the core and peripheral modules. Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X BLOCK DIAGRAM



Note 1: This feature or peripheral is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.
2: This feature or peripheral is only available on dsPIC33EPXXXGP/MC50X devices.

2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to 3 MHz < FIN < 5.5 MHz to comply with device PLL start-up conditions. This means that if the external oscillator frequency is outside this range, the application must start-up in the FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV and PLLFBD, to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source. Note that clock switching must be enabled in the device Configuration Word.

2.8 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic low state.

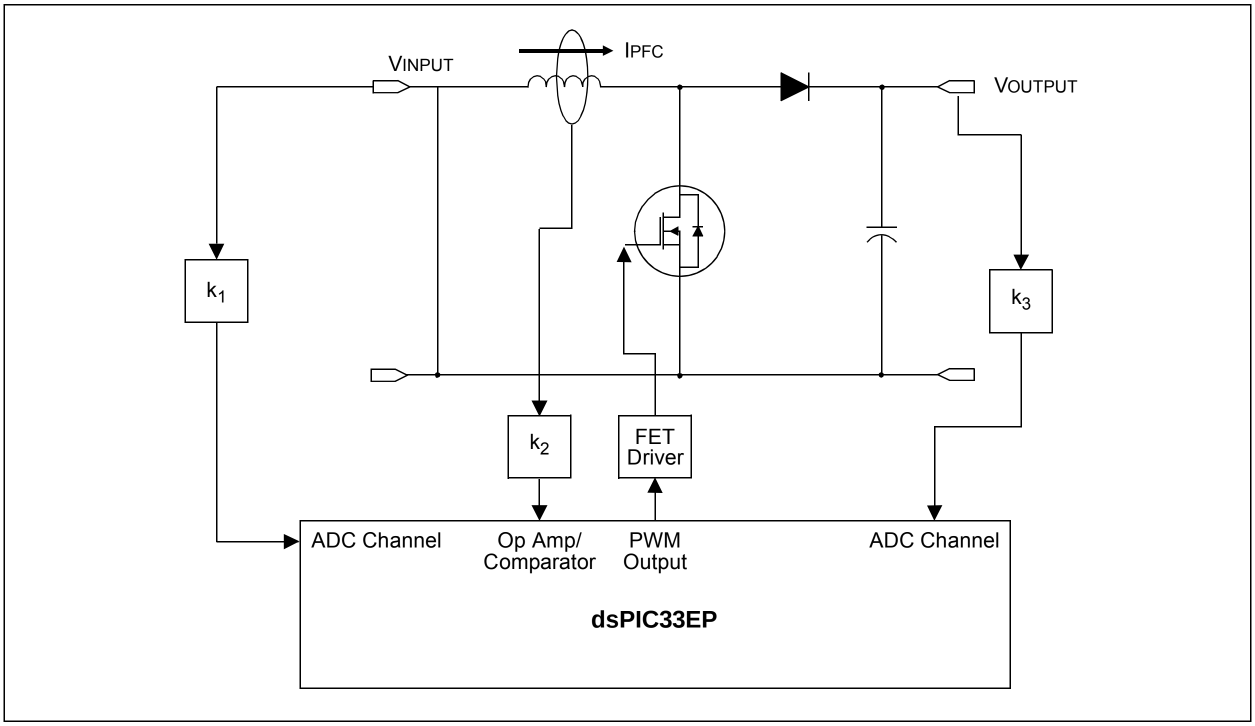
Alternatively, connect a 1k to 10k resistor between VSS and unused pins, and drive the output to logic low.

2.9 Application Examples

- Induction heating
- Uninterruptable Power Supplies (UPS)
- DC/AC inverters
- Compressor motor control
- Washing machine 3-phase motor control
- BLDC motor control
- Automotive HVAC, cooling fans, fuel pumps
- Stepper motor control
- Audio and fluid sensor monitoring
- Camera lens focus and stability control
- Speech (playback, hands-free kits, answering machines, VoIP)
- Consumer audio
- Industrial and building control (security systems and access control)
- Barcode reading
- Networking: LAN switches, gateways
- Data storage device management
- Smart cards and smart card readers

Examples of typical application connections are shown in Figure 2-4 through Figure 2-8.

FIGURE 2-4: BOOST CONVERTER IMPLEMENTATION



REGISTER 3-2: CORCON: CORE CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-0
VAR	—	US1(1)	US0(1)	EDT(1,2)	DL2(1)	DL1(1)	DL0(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-0	R/C-0	R-0	R/W-0	R/W-0
SATA(1)	SATB(1)	SATDW(1)	ACCSAT(1)	IPL3(3)	SFA	RND(1)	IF(1)
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **VAR:** Variable Exception Processing Latency Control bit
1 = Variable exception processing latency is enabled
0 = Fixed exception processing latency is enabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13-12 **US<1:0>:** DSP Multiply Unsigned/Signed Control bits(1)
11 = Reserved
10 = DSP engine multiplies are mixed-sign
01 = DSP engine multiplies are unsigned
00 = DSP engine multiplies are signed

bit 11 **EDT:** Early DO Loop Termination Control bit(1,2)
1 = Terminates executing DO loop at end of current loop iteration
0 = No effect

bit 10-8 **DL<2:0>:** DO Loop Nesting Level Status bits(1)
111 = 7 DO loops are active
•
•
•
001 = 1 DO loop is active
000 = 0 DO loops are active

bit 7 **SATA:** ACCA Saturation Enable bit(1)
1 = Accumulator A saturation is enabled
0 = Accumulator A saturation is disabled

bit 6 **SATB:** ACCB Saturation Enable bit(1)
1 = Accumulator B saturation is enabled
0 = Accumulator B saturation is disabled

bit 5 **SATDW:** Data Space Write from DSP Engine Saturation Enable bit(1)
1 = Data Space write saturation is enabled
0 = Data Space write saturation is disabled

bit 4 **ACCSAT:** Accumulator Saturation Mode Select bit(1)
1 = 9.31 saturation (super saturation)
0 = 1.31 saturation (normal saturation)

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit 3(3)
1 = CPU Interrupt Priority Level is greater than 7
0 = CPU Interrupt Priority Level is 7 or less

Note 1: This bit is available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.
2: This bit is always read as ‘0’.
3: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

6.1 Reset Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

> **Note:** In the event you are not able to access the product page using the link above, enter this URL in your browser:
> http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

6.1.1 KEY RESOURCES

- **"Reset"** (DS70602) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

TABLE 7-1: INTERRUPT VECTOR DETAILS

Interrupt Source	Vector #	IRQ #	IVT Address	Interrupt Bit Location		
				Flag	Enable	Priority
Highest Natural Order Priority						
INT0 – External Interrupt 0	8	0	0x000014	IFS0<0>	IEC0<0>	IPC0<2:0>
IC1 – Input Capture 1	9	1	0x000016	IFS0<1>	IEC0<1>	IPC0<6:4>
OC1 – Output Compare 1	10	2	0x000018	IFS0<2>	IEC0<2>	IPC0<10:8>
T1 – Timer1	11	3	0x00001A	IFS0<3>	IEC0<3>	IPC0<14:12>
DMA0 – DMA Channel 0	12	4	0x00001C	IFS0<4>	IEC0<4>	IPC1<2:0>
IC2 – Input Capture 2	13	5	0x00001E	IFS0<5>	IEC0<5>	IPC1<6:4>
OC2 – Output Compare 2	14	6	0x000020	IFS0<6>	IEC0<6>	IPC1<10:8>
T2 – Timer2	15	7	0x000022	IFS0<7>	IEC0<7>	IPC1<14:12>
T3 – Timer3	16	8	0x000024	IFS0<8>	IEC0<8>	IPC2<2:0>
SPI1E – SPI1 Error	17	9	0x000026	IFS0<9>	IEC0<9>	IPC2<6:4>
SPI1 – SPI1 Transfer Done	18	10	0x000028	IFS0<10>	IEC0<10>	IPC2<10:8>
U1RX – UART1 Receiver	19	11	0x00002A	IFS0<11>	IEC0<11>	IPC2<14:12>
U1TX – UART1 Transmitter	20	12	0x00002C	IFS0<12>	IEC0<12>	IPC3<2:0>
AD1 – ADC1 Convert Done	21	13	0x00002E	IFS0<13>	IEC0<13>	IPC3<6:4>
DMA1 – DMA Channel 1	22	14	0x000030	IFS0<14>	IEC0<14>	IPC3<10:8>
Reserved	23	15	0x000032	—	—	—
SI2C1 – I2C1 Slave Event	24	16	0x000034	IFS1<0>	IEC1<0>	IPC4<2:0>
MI2C1 – I2C1 Master Event	25	17	0x000036	IFS1<1>	IEC1<1>	IPC4<6:4>
CM – Comparator Combined Event	26	18	0x000038	IFS1<2>	IEC1<2>	IPC4<10:8>
CN – Input Change Interrupt	27	19	0x00003A	IFS1<3>	IEC1<3>	IPC4<14:12>
INT1 – External Interrupt 1	28	20	0x00003C	IFS1<4>	IEC1<4>	IPC5<2:0>
Reserved	29-31	21-23	0x00003E-0x000042	—	—	—
DMA2 – DMA Channel 2	32	24	0x000044	IFS1<8>	IEC1<8>	IPC6<2:0>
OC3 – Output Compare 3	33	25	0x000046	IFS1<9>	IEC1<9>	IPC6<6:4>
OC4 – Output Compare 4	34	26	0x000048	IFS1<10>	IEC1<10>	IPC6<10:8>
T4 – Timer4	35	27	0x00004A	IFS1<11>	IEC1<11>	IPC6<14:12>
T5 – Timer5	36	28	0x00004C	IFS1<12>	IEC1<12>	IPC7<2:0>
INT2 – External Interrupt 2	37	29	0x00004E	IFS1<13>	IEC1<13>	IPC7<6:4>
U2RX – UART2 Receiver	38	30	0x000050	IFS1<14>	IEC1<14>	IPC7<10:8>
U2TX – UART2 Transmitter	39	31	0x000052	IFS1<15>	IEC1<15>	IPC7<14:12>
SPI2E – SPI2 Error	40	32	0x000054	IFS2<0>	IEC2<0>	IPC8<2:0>
SPI2 – SPI2 Transfer Done	41	33	0x000056	IFS2<1>	IEC2<1>	IPC8<6:4>
C1RX – CAN1 RX Data Ready(1)	42	34	0x000058	IFS2<2>	IEC2<2>	IPC8<10:8>
C1 – CAN1 Event(1)	43	35	0x00005A	IFS2<3>	IEC2<3>	IPC8<14:12>
DMA3 – DMA Channel 3	44	36	0x00005C	IFS2<4>	IEC2<4>	IPC9<2:0>
IC3 – Input Capture 3	45	37	0x00005E	IFS2<5>	IEC2<5>	IPC9<6:4>
IC4 – Input Capture 4	46	38	0x000060	IFS2<6>	IEC2<6>	IPC9<10:8>
Reserved	47-56	39-48	0x000062-0x000074	—	—	—
SI2C2 – I2C2 Slave Event	57	49	0x000076	IFS3<1>	IEC3<1>	IPC12<6:4>
MI2C2 – I2C2 Master Event	58	50	0x000078	IFS3<2>	IEC3<2>	IPC12<10:8>
Reserved	59-64	51-56	0x00007A-0x000084	—	—	—
PSEM – PWM Special Event Match(2)	65	57	0x000086	IFS3<9>	IEC3<9>	IPC14<6:4>

Note 1: This interrupt source is available on dsPIC33EPXXXGP50X and dsPIC33EPXXXMC50X devices only.
2: This interrupt source is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

10.2.1 SLEEP MODE

The following occurs in Sleep mode:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current.
- The Fail-Safe Clock Monitor does not operate, since the system clock source is disabled.
- The LPRC clock continues to run in Sleep mode if the WDT is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals can continue to operate. This includes items such as the Input Change Notification (ICN) on the I/O ports or peripherals that use an external clock input.
- Any peripheral that requires the system clock source for its operation is disabled.

The device wakes up from Sleep mode on any of these events:

- Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep mode, the processor restarts with the same clock source that was active when Sleep mode was entered.

For optimal power savings, the internal regulator and the Flash regulator can be configured to go into Standby when Sleep mode is entered by clearing the VREGS (RCON<8>) and VREGSF (RCON<11>) bits (default configuration).

If the application requires a faster wake-up time, and can accept higher current requirements, the VREGS (RCON<8>) and VREGSF (RCON<11>) bits can be set to keep the internal regulator and the Flash regulator active during Sleep mode.

10.2.2 IDLE MODE

The following occurs in Idle mode:

- The CPU stops executing instructions.
- The WDT is automatically cleared.
- The system clock source remains active. By default, all peripheral modules continue to operate normally from the system clock source, but can also be selectively disabled (see **Section 10.4 "Peripheral Module Disable"**).
- If the WDT or FSCM is enabled, the LPRC also remains active.

The device wakes from Idle mode on any of these events:

- Any interrupt that is individually enabled
- Any device Reset
- A WDT time-out

On wake-up from Idle mode, the clock is reapplied to the CPU and instruction execution will begin (2-4 clock cycles later), starting with the instruction following the `PWRSAV` instruction or the first instruction in the Interrupt Service Routine (ISR).

All peripherals also have the option to discontinue operation when Idle mode is entered to allow for increased power savings. This option is selectable in the control register of each peripheral; for example, the TSIDL bit in the Timer1 Control register (T1CON<13>).

10.2.3 INTERRUPTS COINCIDENT WITH POWER SAVE INSTRUCTIONS

Any interrupt that coincides with the execution of a `PWRSAV` instruction is held off until entry into Sleep or Idle mode has completed. The device then wakes up from Sleep or Idle mode.

REGISTER 11-8: RPINR14: PERIPHERAL PIN SELECT INPUT REGISTER 14 (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	QEB1R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	QEA1R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**Unimplemented:** Read as ‘`0`’
bit 14-8	**QEB1R<6:0>:** Assign B (QEB) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers) `1111001` = Input tied to RPI121 . . . `0000001` = Input tied to CMP1 `0000000` = Input tied to VSS
bit 7	**Unimplemented:** Read as ‘`0`’
bit 6-0	**QEA1R<6:0>:** Assign A (QEA) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers) `1111001` = Input tied to RPI121 . . . `0000001` = Input tied to CMP1 `0000000` = Input tied to VSS

REGISTER 16-13: IOCONx: PWMx I/O CONTROL REGISTER(2) (CONTINUED)

bit 1	**SWAP:** SWAP PWMxH and PWMxL Pins bit `1` = PWMxH output signal is connected to PWMxL pins; PWMxL output signal is connected to PWMxH pins `0` = PWMxH and PWMxL pins are mapped to their respective pins
bit 0	**OSYNC:** Output Override Synchronization bit `1` = Output overrides via the OVRDAT<1:0> bits are synchronized to the PWMx period boundary `0` = Output overrides via the OVDDAT<1:0> bits occur on the next CPU clock boundary

Note 1: These bits should not be changed after the PWMx module is enabled (PTEN = `1`).

2: If the PWMLOCK Configuration bit (FOSCSEL<6>) is a ‘`1`’, the IOCONx register can only be written after the unlock sequence has been executed.

REGISTER 16-15: FCLCONx: PWMx FAULT CURRENT-LIMIT CONTROL REGISTER(1)

bit 7-3	**FLTSRC<4:0>:** Fault Control Signal Source Select for PWM Generator # bits `11111` = Fault 32 **(default)** `11110` = Reserved • • • `01100` = Reserved `01011` = Comparator 4 `01010` = Op Amp/Comparator 3 `01001` = Op Amp/Comparator 2 `01000` = Op Amp/Comparator 1 `00111` = Reserved `00110` = Reserved `00101` = Reserved `00100` = Reserved `00011` = Fault 4 `00010` = Fault 3 `00001` = Fault 2 `00000` = Fault 1
bit 2	**FLTPOL:** Fault Polarity for PWM Generator # bit(2) `1` = The selected Fault source is active-low `0` = The selected Fault source is active-high
bit 1-0	**FLTMOD<1:0>:** Fault Mode for PWM Generator # bits `11` = Fault input is disabled `10` = Reserved `01` = The selected Fault source forces PWMxH, PWMxL pins to FLTDAT values (cycle) `00` = The selected Fault source forces PWMxH, PWMxL pins to FLTDAT values (latched condition)

Note 1: If the PWMLOCK Configuration bit (FOSCSEL<6>) is a ‘`1`’, the IOCONx register can only be written after the unlock sequence has been executed.

2: These bits should be changed only when PTEN = `0`. Changing the clock selection during operation will yield unpredictable results.

18.1 SPI Helpful Tips

1. In Frame mode, if there is a possibility that the master may not be initialized before the slave:
    a) If FRMPOL (SPIxCON2<13>) = `1`, use a pull-down resistor on $\overline{\text{SSx}}$.
    b) If FRMPOL = `0`, use a pull-up resistor on $\overline{\text{SSx}}$.

> **Note:** This insures that the first frame transmission after initialization is not shifted or corrupted.

2. In Non-Framed 3-Wire mode, (i.e., not using $\overline{\text{SSx}}$ from a master):
    a) If CKP (SPIxCON1<6>) = `1`, always place a pull-up resistor on $\overline{\text{SSx}}$.
    b) If CKP = `0`, always place a pull-down resistor on $\overline{\text{SSx}}$.

> **Note:** This will insure that during power-up and initialization the master/slave will not lose Sync due to an errant SCKx transition that would cause the slave to accumulate data shift errors for both transmit and receive appearing as corrupted data.

3. FRMEN (SPIxCON2<15>) = `1` and SSEN (SPIxCON1<7>) = `1` are exclusive and invalid. In Frame mode, SCKx is continuous and the Frame Sync pulse is active on the $\overline{\text{SSx}}$ pin, which indicates the start of a data frame.

> **Note:** Not all third-party devices support Frame mode timing. Refer to the SPIx specifications in **Section 30.0 "Electrical Characteristics"** for details.

4. In Master mode only, set the SMP bit (SPIxCON1<9>) to a '`1`' for the fastest SPIx data rate possible. The SMP bit can only be set at the same time or after the MSTEN bit (SPIxCON1<5>) is set.

To avoid invalid slave read data to the master, the user's master software must ensure enough time for slave software to fill its write buffer before the user application initiates a master write/read cycle. It is always advisable to preload the SPIxBUF Transmit register in advance of the next master transaction cycle. SPIxBUF is transferred to the SPIx Shift register and is empty once the data transmission begins.

18.2 SPI Resources

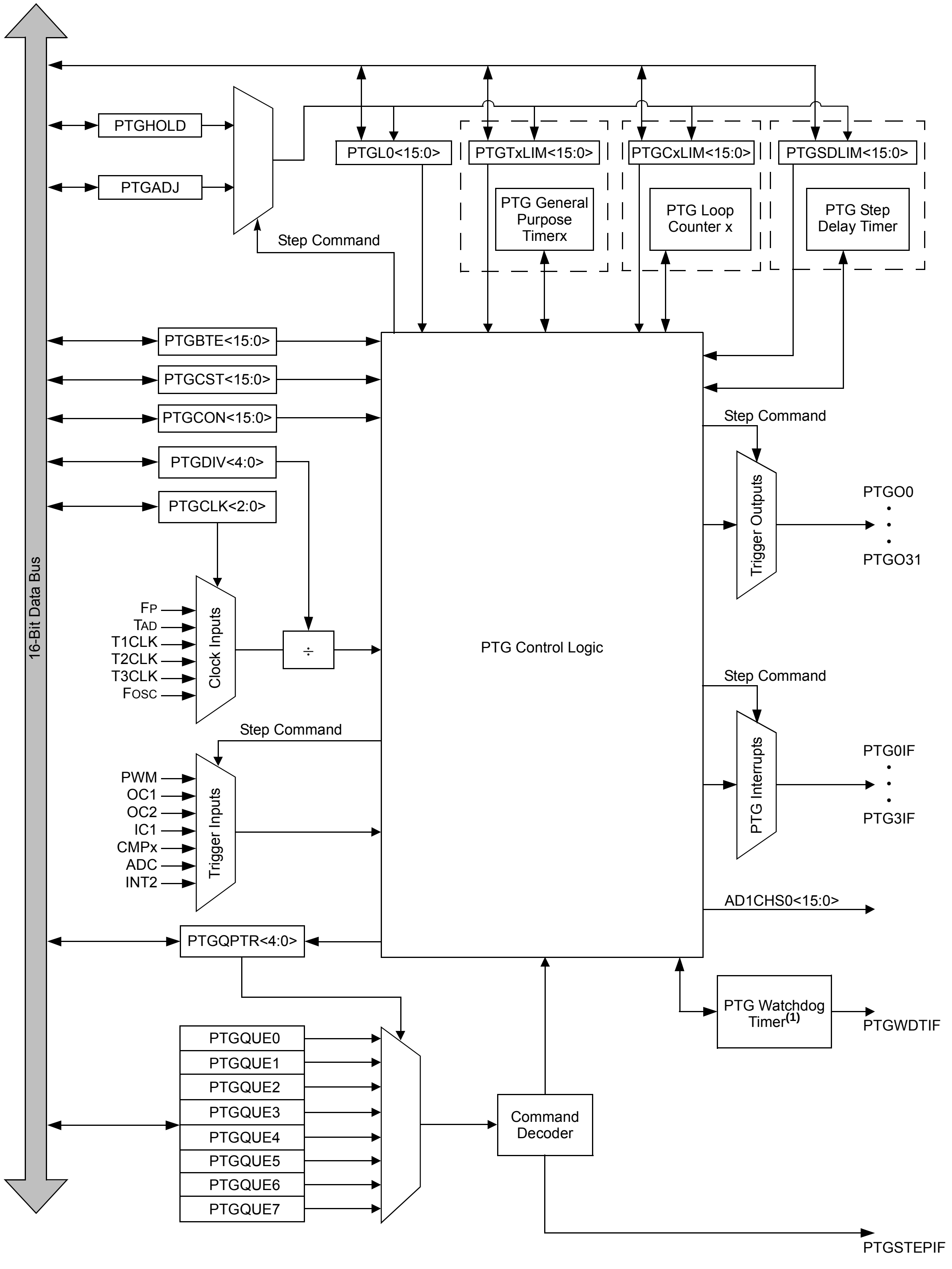
Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

> **Note:** In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

18.2.1 KEY RESOURCES

- **"Serial Peripheral Interface (SPI)"** (DS70569) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

FIGURE 24-1: PTG BLOCK DIAGRAM



Note 1: This is a dedicated Watchdog Timer for the PTG module and is independent of the device Watchdog Timer.

REGISTER 24-8: PTGC1LIM: PTG COUNTER 1 LIMIT REGISTER[1]

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGC1LIM<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGC1LIM<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **PTGC1LIM<15:0>:** PTG Counter 1 Limit Register bits

May be used to specify the loop count for the `PTGJMPC1` Step command or as a limit register for the General Purpose Counter 1.

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = `1` and PTGSTRT = `1`).

REGISTER 24-9: PTGHOLD: PTG HOLD REGISTER[1]

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGHOLD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGHOLD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **PTGHOLD<15:0>:** PTG General Purpose Hold Register bits

Holds user-supplied data to be copied to the PTGTxLIM, PTGCxLIM, PTGSDLIM or PTGL0 registers with the `PTGCOPY` command.

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = `1` and PTGSTRT = `1`).

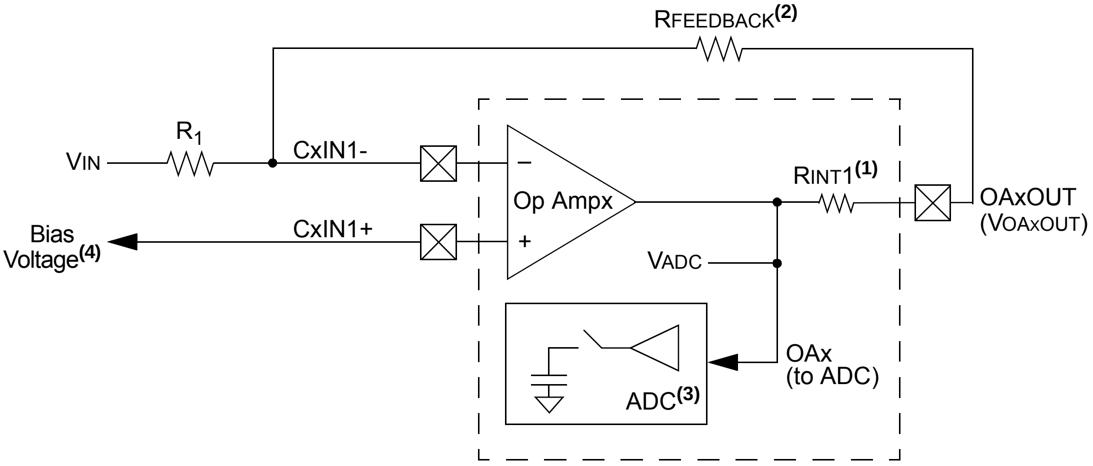
25.1 Op Amp Application Considerations

There are two configurations to take into consideration when designing with the op amp modules that are available in the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices. Configuration A (see Figure 25-6) takes advantage of the internal connection to the ADC module to route the output of the op amp directly to the ADC for measurement. Configuration B (see Figure 25-7) requires that the designer externally route the output of the op amp (OAxOUT) to a separate analog input pin (ANy) on the device. Table 30-55 in **Section 30.0 “Electrical Characteristics”** describes the performance characteristics for the op amps, distinguishing between the two configuration types where applicable.

25.1.1 OP AMP CONFIGURATION A

Figure 25-6 shows a typical inverting amplifier circuit taking advantage of the internal connections from the op amp output to the input of the ADC. The advantage of this configuration is that the user does not need to consume another analog input (ANy) on the device, and allows the user to simultaneously sample all three op amps with the ADC module, if needed. However, the presence of the internal resistance, RINT1, adds an error in the feedback path. Since RINT1 is an internal resistance, in relation to the op amp output (VOAXOUT) and ADC internal connection (VADC), RINT1 must be included in the numerator term of the transfer function. See Table 30-53 in **Section 30.0 “Electrical Characteristics”** for the typical value of RINT1. Table 30-60 and Table 30-61 in **Section 30.0 “Electrical Characteristics”** describe the minimum sample time (TSAMP) requirements for the ADC module in this configuration. Figure 25-6 also defines the equations that should be used when calculating the expected voltages at points, VADC and VOAXOUT.

FIGURE 25-6: OP AMP CONFIGURATION A



$$V_{ADC} = \left(\frac{R_{FEEDBACK} + R_{INT1}}{R_1}\right)(\ Bias\ Voltage - V_{IN}\ )$$

$$V_{OAxOUT} = \left(\frac{R_{FEEDBACK}}{R_1}\right)(\ Bias\ Voltage - V_{IN}\ )$$

Note 1: See Table 30-53 for the Typical value.

2: See Table 30-53 for the Minimum value for the feedback resistor.

3: See Table 30-60 and Table 30-61 for the minimum sample time (TSAMP).

4: CVREF1O or CVREF2O are two options that are available for supplying bias voltage to the op amps.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles[2]	Status Flags Affected
52	`MUL`	`MUL.SS Wb,Ws,Wnd`	{Wnd + 1, Wnd} = signed(Wb) * signed(Ws)	1	1	None
		`MUL.SS Wb,Ws,Acc`[1]	Accumulator = signed(Wb) * signed(Ws)	1	1	None
		`MUL.SU Wb,Ws,Wnd`	{Wnd + 1, Wnd} = signed(Wb) * unsigned(Ws)	1	1	None
		`MUL.SU Wb,Ws,Acc`[1]	Accumulator = signed(Wb) * unsigned(Ws)	1	1	None
		`MUL.SU Wb,#lit5,Acc`[1]	Accumulator = signed(Wb) * unsigned(lit5)	1	1	None
		`MUL.US Wb,Ws,Wnd`	{Wnd + 1, Wnd} = unsigned(Wb) * signed(Ws)	1	1	None
		`MUL.US Wb,Ws,Acc`[1]	Accumulator = unsigned(Wb) * signed(Ws)	1	1	None
		`MUL.UU Wb,Ws,Wnd`	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(Ws)	1	1	None
		`MUL.UU Wb,#lit5,Acc`[1]	Accumulator = unsigned(Wb) * unsigned(lit5)	1	1	None
		`MUL.UU Wb,Ws,Acc`[1]	Accumulator = unsigned(Wb) * unsigned(Ws)	1	1	None
		`MULW.SS Wb,Ws,Wnd`	Wnd = signed(Wb) * signed(Ws)	1	1	None
		`MULW.SU Wb,Ws,Wnd`	Wnd = signed(Wb) * unsigned(Ws)	1	1	None
		`MULW.US Wb,Ws,Wnd`	Wnd = unsigned(Wb) * signed(Ws)	1	1	None
		`MULW.UU Wb,Ws,Wnd`	Wnd = unsigned(Wb) * unsigned(Ws)	1	1	None
		`MUL.SU Wb,#lit5,Wnd`	{Wnd + 1, Wnd} = signed(Wb) * unsigned(lit5)	1	1	None
		`MUL.SU Wb,#lit5,Wnd`	Wnd = signed(Wb) * unsigned(lit5)	1	1	None
		`MUL.UU Wb,#lit5,Wnd`	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(lit5)	1	1	None
		`MUL.UU Wb,#lit5,Wnd`	Wnd = unsigned(Wb) * unsigned(lit5)	1	1	None
		`MUL f`	W3:W2 = f * WREG	1	1	None

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

FIGURE 30-11: TIMERQ (QEI MODULE) EXTERNAL CLOCK TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

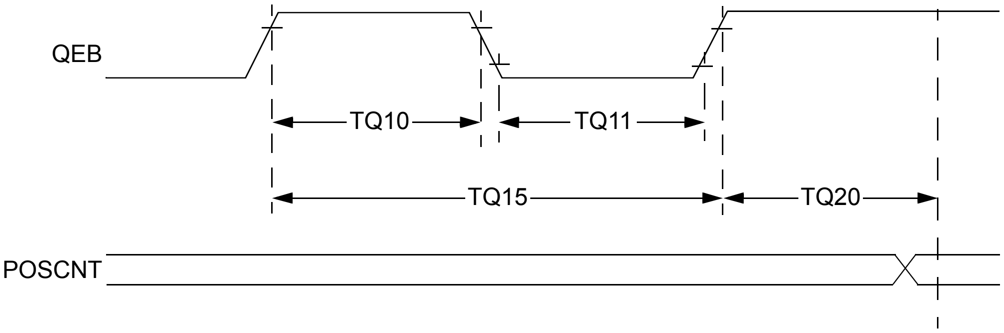


TABLE 30-30: QEI MODULE EXTERNAL CLOCK TIMING REQUIREMENTS (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

AC CHARACTERISTICS				**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**[1]		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TQ10	TtQH	TQCK High Time	Synchronous, with prescaler	Greater of 12.5 + 25 or (0.5 TCY/N) + 25	—	—	ns	Must also meet Parameter TQ15
TQ11	TtQL	TQCK Low Time	Synchronous, with prescaler	Greater of 12.5 + 25 or (0.5 TCY/N) + 25	—	—	ns	Must also meet Parameter TQ15
TQ15	TtQP	TQCP Input Period	Synchronous, with prescaler	Greater of 25 + 50 or (1 TCY/N) + 50	—	—	ns	
TQ20	TCKEXTMRL	Delay from External TQCK Clock Edge to Timer Increment		—	1	TCY	—	

Note 1: These parameters are characterized but not tested in manufacturing.

31.0 HIGH-TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 30.0 “Electrical Characteristics”** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, Parameter DC10 in **Section 30.0 “Electrical Characteristics”** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X high-temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias(2)	-40°C to +150°C
Storage temperature	-65°C to +160°C
Voltage on VDD with respect to VSS	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to VSS(3)	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD < 3.0V(3)	-0.3V to 3.6V
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 3.0V(3)	-0.3V to 5.5V
Maximum current out of VSS pin	60 mA
Maximum current into VDD pin(4)	60 mA
Maximum junction temperature	+155°C
Maximum current sourced/sunk by any 4x I/O pin	10 mA
Maximum current sourced/sunk by any 8x I/O pin	15 mA
Maximum current sunk by all ports combined	70 mA
Maximum current sourced by all ports combined(4)	70 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

2: AEC-Q100 reliability testing for devices intended to operate at +150°C is 1,000 hours. Any design in which the total operating time from +125°C to +150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

3: Refer to the **“Pin Diagrams”** section for 5V tolerant pins.

4: Maximum allowable current is a function of device maximum power dissipation (see Table 31-2).

31.2 AC Characteristics and Timing Parameters

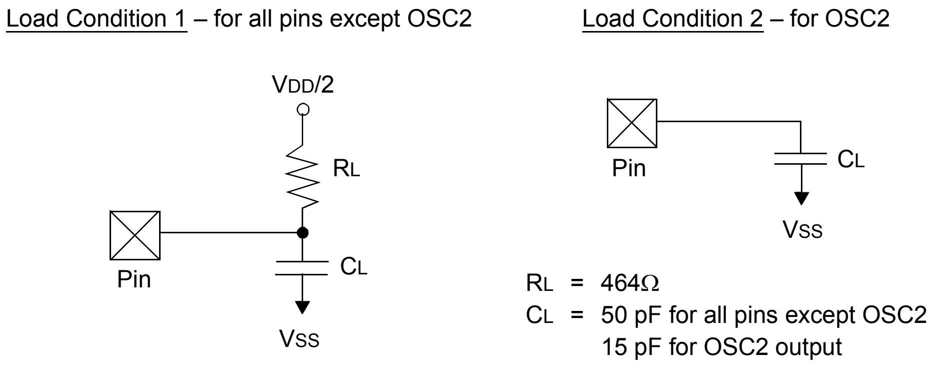
The information contained in this section defines dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X AC characteristics and timing parameters for high-temperature devices. However, all AC timing specifications in this section are the same as those in **Section 30.2 "AC Characteristics and Timing Parameters"**, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, Parameter OS53 in **Section 30.2 "AC Characteristics and Timing Parameters"** is the Industrial and Extended temperature equivalent of HOS53.

TABLE 31-9: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V** **(unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C Operating voltage VDD range as described in Table 31-1.

FIGURE 31-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



Load Condition 1 – for all pins except OSC2

Load Condition 2 – for OSC2

RL = 464Ω

CL = 50 pF for all pins except OSC2
15 pF for OSC2 output

TABLE 31-10: PLL CLOCK TIMING SPECIFICATIONS

<table>
<tr><td colspan="3">AC CHARACTERISTICS</td><td colspan="5">Standard Operating Conditions: 3.0V to 3.6V
(unless otherwise stated)
Operating temperature -40°C ≤ TA ≤ +150°C</td></tr>
<tr><td>Param No.</td><td>Symbol</td><td>Characteristic</td><td>Min</td><td>Typ</td><td>Max</td><td>Units</td><td>Conditions</td></tr>
<tr><td>HOS53</td><td>DCLK</td><td>CLKO Stability (Jitter)(1)</td><td>-5</td><td>0.5</td><td>5</td><td>%</td><td>Measured over 100 ms period</td></tr>
</table>

Note 1: These parameters are characterized by similarity, but are not tested in manufacturing. This specification is based on clock cycle by clock cycle measurements. To calculate the effective jitter for individual time bases or communication clocks use this formula:

$$\text{Peripheral Clock Jitter} = \frac{D_{CLK}}{\sqrt{\left(\frac{F_{OSC}}{\text{Peripheral Bit Rate Clock}}\right)}}$$

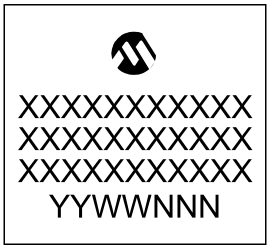
For example: FOSC = 32 MHz, DCLK = 5%, SPIx bit rate clock (i.e., SCKx) is 2 MHz.

$$\text{SPI SCK Jitter} = \left[\frac{D_{CLK}}{\sqrt{\left(\frac{32\ MHz}{2\ MHz}\right)}}\right] = \left[\frac{5\%}{\sqrt{16}}\right] = \left[\frac{5\%}{4}\right] = 1.25\%$$

NOTES:

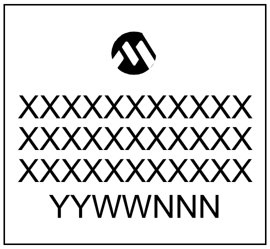
33.1 Package Marking Information (Continued)

48-Lead UQFN (6x6x0.5 mm)



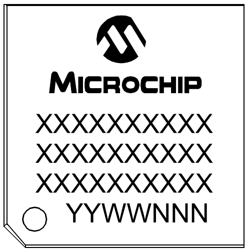
Example

64-Lead QFN (9x9x0.9 mm)



Example

64-Lead TQFP (10x10x1 mm)



Example